

HSC88

Silicon Schottky Barrier Diode for Various Detector, Mixer

REJ03G0624-0100 (Previous: ADE-208-826) Rev.1.00 Apr 12, 2005

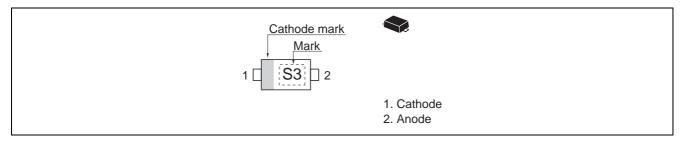
Features

- Low capacitance. (C = 0.8 pF max)
- Low forward voltage.
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Cathode Mark	Package Name	Package Code (Previous Code)
HSC88	S3	UFP	PWSF0002ZA-A (UFP)

Pin Arrangement





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
ltem	Symbol	Value	Unit
Reverse voltage	V _R	10	V
Average rectified current	Io	15	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

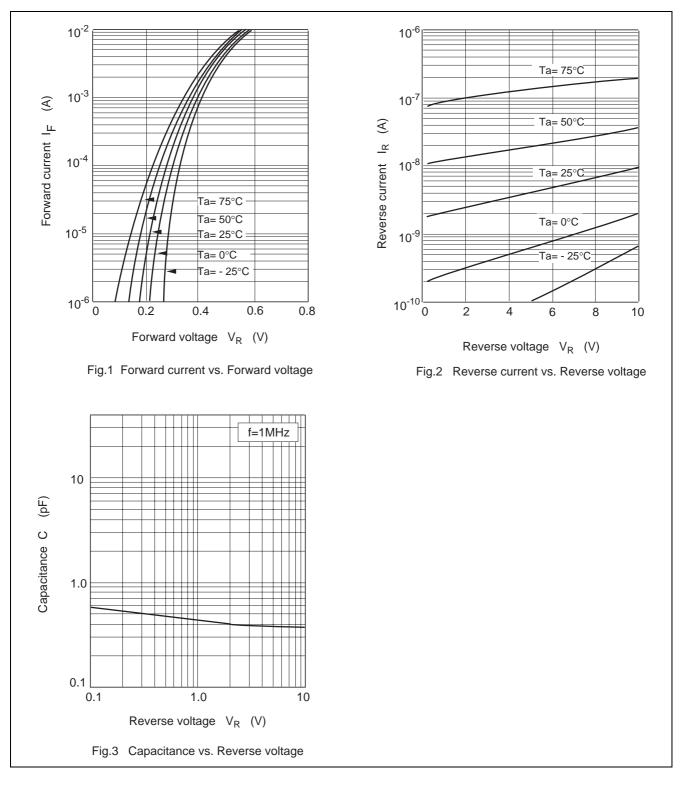
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
ltem	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _{F1}	0.350	—	0.420	V	I _F = 1 mA
	V _{F2}	0.500	—	0.580		I _F = 10 mA
Reverse current	I _{R1}	_	—	0.2	μA	V _R = 2 V
	I _{R2}	_	—	10		V _R = 10 V
Capacitance	С	_	—	0.80	pF	$V_{R} = 0 V, f = 1 MHz$
ESD-Capability *1	—	30	—	—	Ω	C = 200 pF, Both forward and
						reverse direction 1 pulse.

Note: 1. Failure criterion ; $I_R \ge 0.4 \mu A$ at V_R =2 V

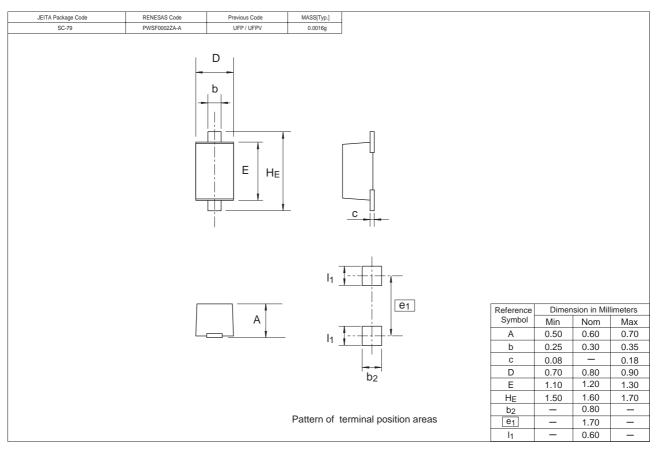


Main Characteristic





Package Dimensions





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